Analog Switch, High Bandwidth, Dual SPDT

The NLAS4717 is an advanced CMOS analog switch fabricated in sub-micron silicon gate CMOS technology. The device is a dual independent Single Pole Double Throw (SPDT) switch featuring two low $R_{DS(on)}$ of 4.5 Ω at 3.0 V.

The device also features guaranteed Break-Before-Make (BBM) switching, assuring the switches never short the driver.

The NLAS4717 is available in two small size packages:

Micro10: 3.0 x 5.0 mm
 Flip-Chip-10: 2.0 x 1.5 mm

Features

- Low R_{DS(on)}: 4.5 Ω @ 3.0 V
- Matching Between the Switches $\pm 0.5 \Omega$
- Wide Low Voltage Range: 1.8 V to 5.5 V
- High Bandwidth > 40 MHz
- 1.65 V to 5.5 V Operating Range
- Low Threshold Voltages on Pins 4 and 8 (CTRL Pins)
- Ultra-Low Charge Injection ≤ 6.0 pC
- Low Standby Current $I_{CC} = 1.0 \text{ nA (Max)} @ T_A = 25^{\circ}C$
- OVT* on Pins 4 and 8 (CTRL Logic Pins)
- Pb-Free Packages are Available

Typical Applications

- Cell Phones
- PDAs
- MP3s
- Digital Still Cameras

Important Information

• ESD Protection:

HBM = 2000 V, MM = 200 V

- Latchup Max Rating: 200 mA (Per JEDEC EIA/JESD78)
- Pin-to-Pin Compatible with MAX4717

*OVT

 Overvoltage Tolerance (OVT) specific pins to operate higher than normal supply voltages, with no damage to the devices or to signal integrity.

1



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MARKING DIAGRAMS



FLIP-CHIP-10 CASE 489AA





Micro10 CASE 846B



A = Assembly Location Y = Year W, WW = Work Week

= Pb-Free Package

FUNCTION TABLE

IN_	ı	NO_	NC_
0		OFF	ON
1		ON	OFF

ORDERING INFORMATION

Device	Package	Shipping [†]
NLAS4717FCT1	Flip-Chip-10	3000 / Tape & Reel
NLAS4717FCT1G	Flip-Chip-10 (Pb-Free)	3000 / Tape & Reel
NLAS4717MR2	Micro10	4000 / Tape & Reel
NLAS4717MR2G	Micro10 (Pb-Free)	4000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

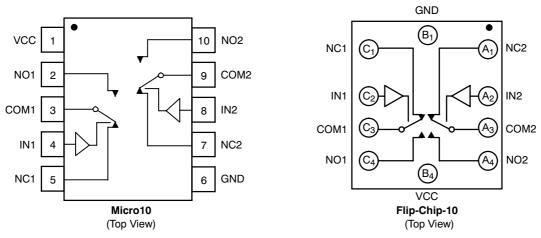


Figure 1. Device Circuit Diagrams and Pin Configurations

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V+	Positive DC Supply Voltage	-0.5 to +7.0	V
V _{IS}	Analog Input Voltage (V _{NO} , V _{NC} , or V _{COM}) (Note 1)	$-0.5 \le V_{IS} \le V_{CC} + 0.5$	٧
V _{IN}	Digital Select Input Voltage	$-0.5 \le V_{I} \le +7.0$	٧
I _{IK}	DC Current, Into or Out of Any Pin (Continuous)	±100	mA
I _{PK}	Peak Current (10% Duty Cycle)	±200	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V+	DC Supply Voltage		1.8	5.5	٧
V _{IN}	Digital Select Input Voltage	GND	5.5	V	
V _{IS}	Analog Input Voltage (NC, NO, COM)			V _{CC}	V
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Rise or Fall Time, SELECT	$I_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $I_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0	100 20	ns/V

ANALOG SWITCH DC CHARACTERISTICS

				-40 °C t	to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Max	Unit
V _{IH}	Input Logic High Voltage	V _{OUT} = 0.1 V	1.65 to 2.2	V _{CC} x 0.55	-	V
		I _{OUT} ≤ 20 μA	2.7 to 3.6	V _{CC} x 0.5	-	
			4.5 to 5.5	2.0	-	
V _{IL}	Input Logic Low Voltage	V _{OUT} = -V _{CC} - 0.1 V	1.65 to 2.2	-	V _{CC} x 0.2	V
		I _{OUT} ≤ 20 μA	2.7 to 3.6	-	V _{CC} x 0.2	
			4.5 to 5.5	-	0.8	
I _{IN}	Input Leakage Current	V _{IN} – V _{CC} or GND	5.0	-100	+100	nA
V _{CC}	Power Supply Range	All	-	1.65	5.5	V
I _{CC}	Supply Current	V _{IN} = V _{CC} or GND	1.8	-	1.0	μΑ
		I _{OUT} = 0 μA	3.3	-	1.0	
			5.0	-	1.0	
V _{IS}	Analog Signal Range	Key parameter	-	0	V _{CC}	V

^{1.} Signal voltage on NC, NO, and COM exceeding VCC or GND are clamped by the internal diodes. Limit forward diode current to maximum current rating.

ANALOG SWITCH CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

				-	40 °C to +85°	С	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
R _{ON}	ON Resistance (Note 2)	$V_{CC} = 3.0 \text{ V}$ $I_{COM} = 10 \text{ mA}$ $V_{NO} \text{ or } V_{NC} = V_{IH} \text{ or } V_{IL}$	3.0	-		4.5	Ω
		$V_{CC} = 5.0 \text{ V}$ $I_{COM} = 10 \text{ mA}$ $V_{NO} \text{ or } V_{NC} = V_{IH} \text{ or } V_{IL}$	5.0	-		3.5	
ΔR _{ON}	ON Resistance Match Between Channels (Note 2 and 3)	$V_{CC} = 3.6 \text{ V}$ $I_{COM} = 10 \text{ mA}$ $V_{NO} \text{ or } V_{NC} = V_{IH} \text{ or } V_{IL}$	3.6	-	0.1	0.4	Ω
		V_{CC} = 5.5 V I_{COM} = 10 mA V_{NO} or V_{NC} = V_{IH} or V_{IL}	5.5				
R _{FLAT[ON]}	ON Resistance Flatness (Note 4)	$I_{COM} = 10 \text{ mA}$ $V_{IS} = 0 \text{ to } V_{CC}$	3.0	-		1.5	Ω
		$I_{COM} = 10 \text{ mA}$ $V_{IS} = 0 \text{ to } V_{CC}$	5.5	-		1.36	
I _{NO_[OFF]} I _{NC_[OFF]}	NO_, NC_ Off-Leakage Current (Note 5)	$V_{CC} = 3.6 \text{ V}$ $V_{COM} = 0.3 \text{ V or } 3.3 \text{ V}$ $V_{NO} \text{ or } V_{NC} = 0.3 \text{ V or } 3.3 \text{ V}$	3.6	-1.0	0.01	+1.0	nA
		$V_{CC} = 5.5 \text{ V}$ $V_{COM} = 0 \text{ V or } 5.0 \text{ V}$ $V_{NO} \text{ or } V_{NC} = 0 \text{ V or } 5.0 \text{ V}$	5.5	-1.0	0.01	+1.0	
I _{COM_[ON]}	COM_ On-Leakage Current (Note 5)	$V_{CC} = 3.6 \text{ V}$ $V_{COM} = 0.3 \text{ V or } 3.3 \text{ V}$ $V_{NO} \text{ or } V_{NC} = 0.3 \text{ V or } 3.3 \text{ V}$	3.6	-2.0	0.01	+2.0	nA
		$V_{CC} = 5.5 \text{ V}$ $V_{COM} = 0 \text{ V or } 5.0 \text{ V}$ $V_{NO} \text{ or } V_{NC} = 0 \text{ V or } 5.0 \text{ V}$	5.5	-2.0	0.01	+2.0	

ANALOG SWITCH AC CHARACTERISTICS

				-	40 °C to +85°(C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
t _{ON}	Turn-On Time	V_{NC} , $V_{NO} = V_{IH}$ or V_{IL} $R_L = 300 \Omega$, $C_L = 35 pF$ $V_{IN[X]} = V_{IH}$ or V_{IL}	1.8 to 5.5	-	-	30	nS
t _{OFF}	Turn-Off Time	V_{NC} , $V_{NO} = V_{IH}$ or V_{IL} $R_L = 300 \Omega$, $C_L = 35 pF$ $V_{IN[X]} = V_{IH}$ or V_{IL}	1.8 to 5.5	-	-	40	nS
t _{BBM}	Break-Before-Make Time Delay (Note 5)	$V_{NC_{-}}, V_{NO_{-}} = 1.5 \text{ V}$ $R_{L} = 300 \Omega, C_{L} = 35 \text{ pF}$	-	-	8.0	-	nS
t _{SKEW}	Skew (Note 5)	$R_S = 39 \Omega, C_L = 50 pF$	-	-	0.15	2.0	nS

- 2. R_{ON} characterized for V_{CC} range (1.65 V to 5.5 V). 3. $\Delta R_{ON} = R_{ON}(MAX) R_{ON}(MIN)$. 4. $R_{FLAT[ON]} = R_{ON}(MAX) R_{ON}(MIN)$, measured over V_{CC} range. 5. Guaranteed by design.

ANALOG SWITCH APPLICATION CHARACTERISTICS

				-	40 °C to +85°	С	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
Q	Charge Injection	$V_{IN} = V_{CC}$ to GND $R_{In} = 0 \Omega$, $C_L = 1.0 \text{ nF}$ $Q = C_L - \Delta V_{OUT}$	3.0 5.0		6.0 9.0		pC
VISO	Off-Isolation	$f = 10 \text{ MHz}$ $V_{NO_}, V_{NC_} = 1.0 \text{ Vp-p}$ $R_L = 50 \Omega, C_L = 5.0 \text{ pF}$	1.65 to 5.5		-50		dB
		f = 1.0 MHz $V_{NO_}, V_{NC_} = 1.0 \text{ Vp-p}$ $R_L = 50 \Omega, C_L = 5.0 \text{ pF}$			-75		
VCT	Cross-Talk	$f = 10 \text{ MHz}$ $V_{NO_}, V_{NC_} = 1.0 \text{ Vp-p}$ $R_L = 50 \Omega, C_L = 5.0 \text{ pF}$	1.65 to 5.5		-80		dB
		$f = 1.0 \text{ MHz}$ $V_{NO_}, V_{NC_} = 1.0 \text{ Vp-p}$ $R_L = 50 \Omega, C_L = 5.0 \text{ pF}$			-1 10		
BW	On-Channel -3.0 db Bandwidth	Signal = 0 dB $R_L = 50 \Omega$, $C_L = 5.0 pF$	1.8 to 5.0	40		MHz	
THD	Total Harmonic Distortion	V_{COM} = 2.0 Vp-p, RL = 600 Ω , T_A = 25°C	-	0.02		%	
NO_[OFF]	NO_, NC_ OFF-Capacitance	F = 10 MHz	-		30		pF
C _{NO_[ON]} C _{NC_[ON]}	NO_, NC_ ON-Capacitance	F = 10 MHz	-		110		pF

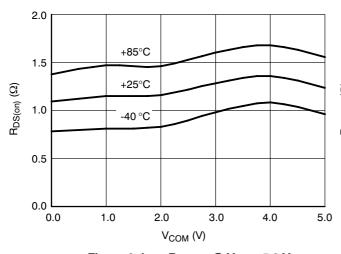


Figure 2. Low R_{DS(on)} @ V_{CC} = 5.0 V

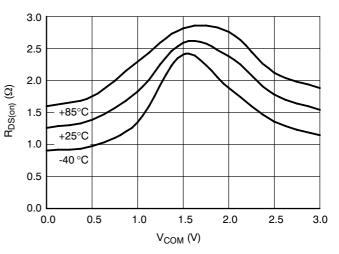


Figure 3. Low R_{DS(on)} @ V_{CC} = 3.0 V

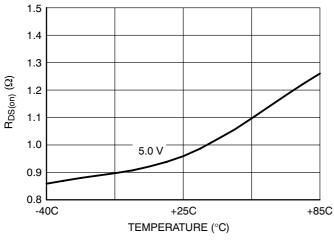


Figure 4. Delta R_{DS(on)} @ V_{CC} = 5.0 V

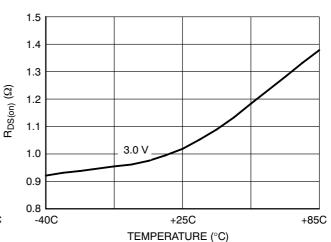


Figure 5. Delta R_{DS(on)} @ V_{CC} = 3.0 V

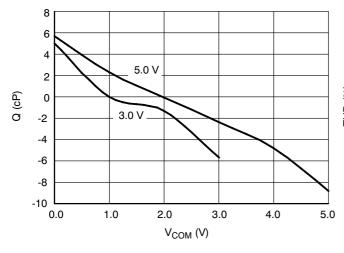


Figure 6. Charge Injection

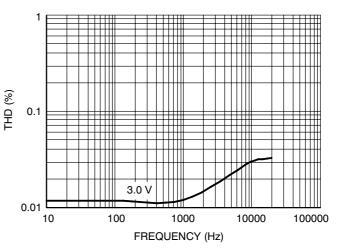
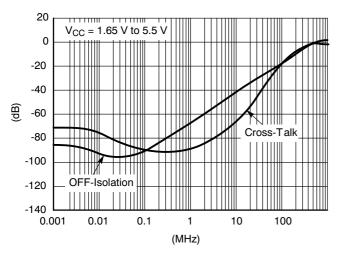


Figure 7. Total Harmonic Distortion



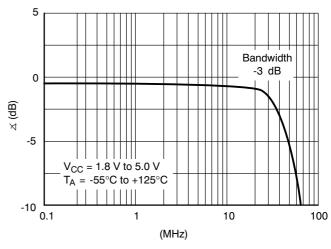
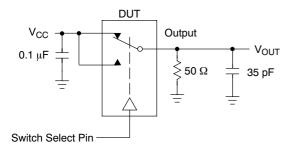


Figure 8. Frequency Response

Figure 9. Bandwidth and Phase



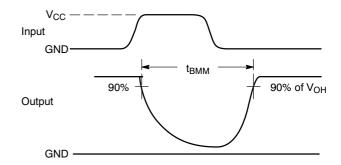
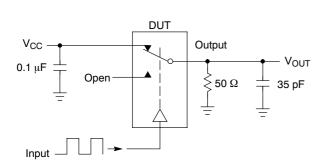


Figure 10. t_{BBM} (Time Break-Before-Make)



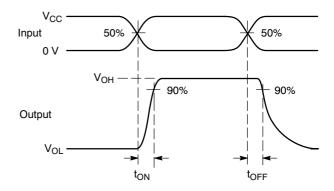
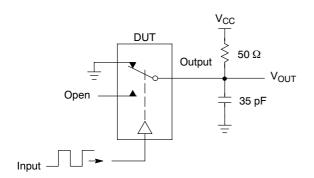


Figure 11. t_{ON}/t_{OFF}



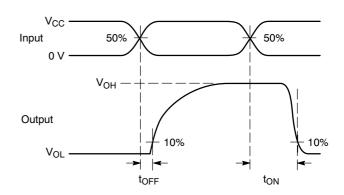
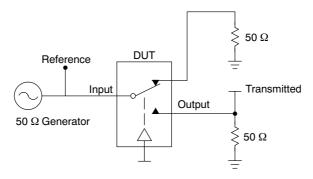


Figure 12. t_{ON}/t_{OFF}



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch. $V_{\rm ISO}$, Bandwidth and $V_{\rm ONL}$ are independent of the input signal direction.

$$\begin{split} &V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log} \bigg(\frac{V_{OUT}}{V_{IN}} \bigg) \text{ for } V_{IN} \text{ at } 100 \text{ kHz} \\ &V_{ONL} = \text{On Channel Loss} = 20 \text{ Log} \left(\frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz to } 50 \text{ MHz} \end{split}$$

Bandwidth (BW) = the frequency 3.0 dB below V_{ONL}

 V_{CT} = Use V_{ISO} setup and test to all other switch analog input/outputs terminated with 50 Ω

Figure 13. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V_{ONL}

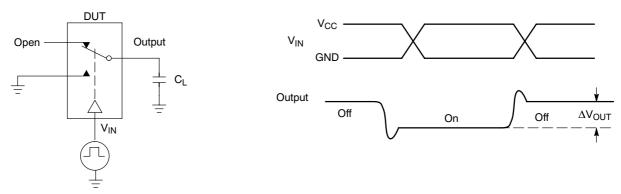


Figure 14. Charge Injection: (Q)

DATE 04 MAY 2004



10 PIN FLIP-CHIP CASE 489AA-01



SCALE 4:1

ISSUE A

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION:
- MILLIMETERS. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN MAX		
Α		0.650	
A1	0.210 0.270		
A2	0.280 0.380		
D	1.965 BSC		
E	1.465	BSC	
ь	0.250	0.350	
e	0.500 BSC		
D1	1.500 BSC		
E1	1.000	BSC	

GENERIC MARKING DIAGRAM*

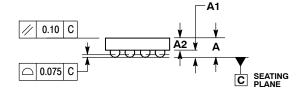


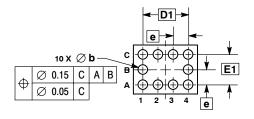
= Specific Device Code XXXX

YY = Year WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

4 X		A B
PIN ONE CORNER	P	E





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Micro10 CASE 846B-03 ISSUE D

DATE 07 DEC 2004

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ANSI Y14-5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- PER SIDE.

 4. DIMENSION "B" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. 846B-01 OBSOLETE. NEW STANDARD 846B-02

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.95	1.10	0.037	0.043
D	0.20	0.30	0.008	0.012
G	0.50	BSC	0.020	BSC
Н	0.05	0.15	0.002	0.006
J	0.10	0.21	0.004	0.008
K	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

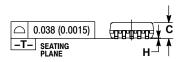
GENERIC MARKING DIAGRAM*

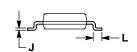


= Device Code XXXX = Assembly Location Α = Year W = Work Week = Pb-Free Package

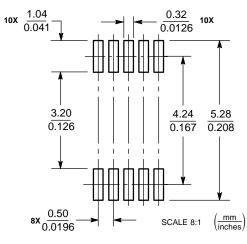
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

< −A- > D 8 PL PIN 1 ID ⊕ 0.08 (0.003) M T B S A S





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Micro₁₀

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DESCRIPTION:	Micro10	PAGE 1 OF 2



DOCUMENT	NUMBER:
98AON03799)D

PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ BY J. HOSKINS.	09 NOV 2000
Α	DIM "D" WAS 0.25-0.4MM/0.10-0.016IN. ADDED NOTE 5. USED ON: WAS 10 LEAD TSSOP, PITCH 0.65 REQ BY J. HOSKINS.	13 NOV 2000
В	CHANGED "USED ON" WAS: 10 LEAD TSSOP, PITCH 0.50MM. REQ BY A. HAMID.	11 JUL 2001
С	CHANGED "D" DIMENSION MAX FROM 0.35 TO 0.30MM AND 0.014 TO 0.012IN. REQ BY D. TRUHITTE.	31 JUL 2003
D	ADDED FOOTPRINT INFORMATION. REQ. BY K. OPPEN.	07 DEC 2004

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